imall

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Contact us

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Panasonic

Zener Diode

DZ2J030×0L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

- Features
- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 3J or 3U

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C Parameter Symbol

Repetitive peak forward current	IFRM	200	mA		
Total power dissipation *1	PT	200	mW		
Electrostatic discharge *2	ESD	±15	kV		
Junction temperature	Tj	150	С°		
Operating ambient temperature	Topr	-40 to +85	°C		
Storage temperature	Tstg	-55 to +150	О°		

Note) *1 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm) Solder in (Recommended land pattern)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)



Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 10 mA			1.0	V	
Zener voltage *1, *2	VZ	IZ = 5 mA	2.85		3.15	V	
Zener operating resistance	RZ	IZ = 5 mA			120	Ω	
Reverse current	IR	VR = 1 V			50	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-2.0		mV/°C	

Rating

Unit

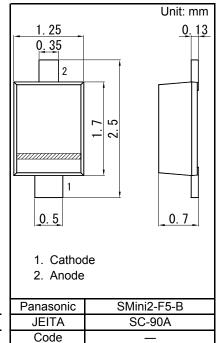
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

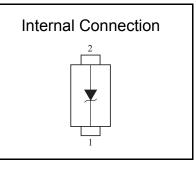
2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 $^\circ\text{C}$ for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 $^\circ$ C).

*2	VZ guaranted 20 ms after current flow	Rank classification	l					
*3	Tj = 25 °C to 150 °C	Code			0			
		Rank			No-rank			
		VZ	2.93	to	3.08	2.85	to	3.15
		Marking symbol	3U		3J			

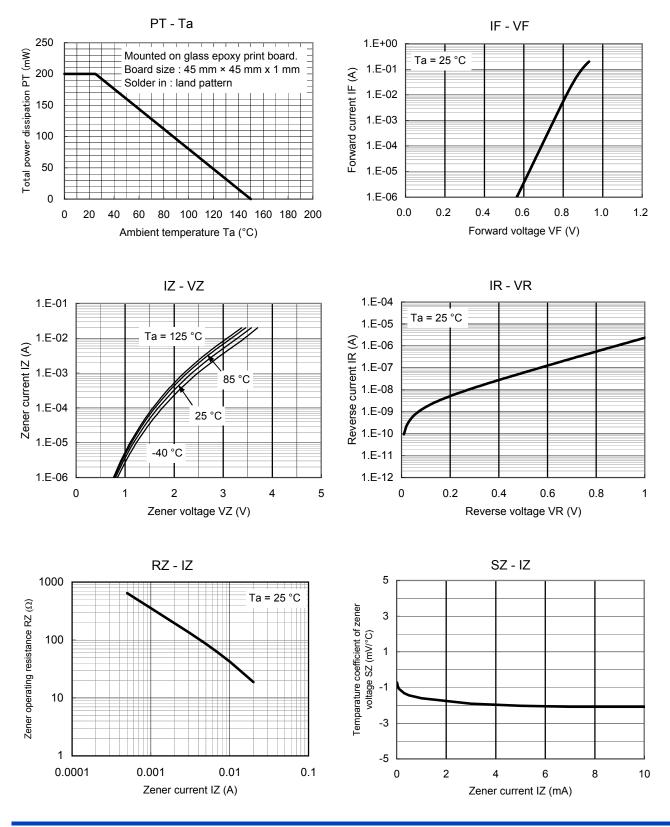






Zener Diode DZ2J030×0L

Technical Data (reference)

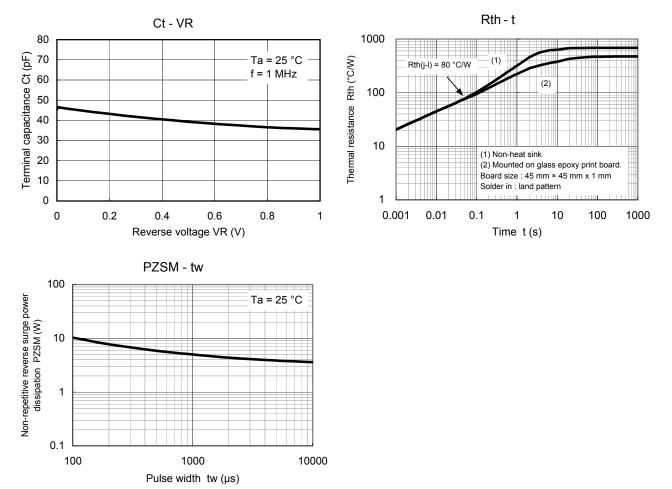


Established : 2009-10-14 Revised : 2013-07-01

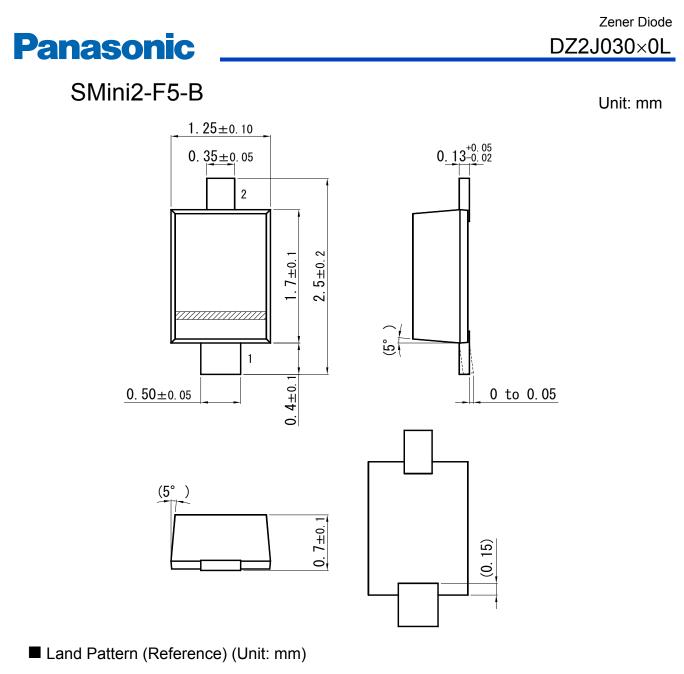


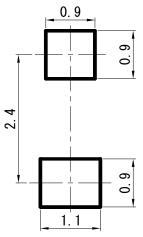
Zener Diode DZ2J030×0L

Technical Data (reference)



Established : 2009-10-14 Revised : 2013-07-01





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